IntelliMAX™ Ultra-Small, Slew-Rate-Controlled Load Switch

FPF1203, FPF1203L, FPF1204

ON Semiconductor®

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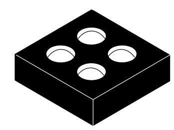


WLCSP4 0.76x0.76x0.586
CASE 567SS

MARKING DIAGRAM

X&K
X&2
&. &Z

XX (QL, QP, QM, VS)	= Specific Device Code
&K	= 2−Digits Lot Run Traceability Code
&2	= 2−Digit Date Code
&.	= Pin One Dot
&Z	= Assembly Pant Code

ORDERING INFORMATION

See detailed ordering and shipping information on page 8 of this data sheet.

Description

The FPF1203 / 03L / 04 are ultra−small integrated IntelliMAX load switches with integrated P−channel switch and analog control features. Integrated slew−rate control prevents inrush current and the resulting excessive voltage drop on the power rail. The input voltage range operates from 1.2 V to 5.5 V to provide power−disconnect capability for post−regulated power rails in portable and consumer products. The low shut−off current allows power designs to meet standby and off−power drain specifications.

The FPF120x are controlled by a logic input (ON pin) compatible with standard CMOS GPIO circuitry found on Field Programmable Gate Array (FPGA) embedded processors. The FPF120x are available in 0.76 mm x 0.76 mm 4−bump WLCSP.

Features

- 1.2 V to 5.5 V Input Voltage Operating Range
- Typical R_{ON}:
  - 45 mΩ at V_{IN} = 5.5 V
  - 55 mΩ at V_{IN} = 3.3 V
  - 90 mΩ at V_{IN} = 1.8 V
  - 185 mΩ at V_{IN} = 1.2 V
- Slew Rate Control with t_R:
  - 100 μs
- Output Discharge Function on FPF1204
- Low <1.5 μA Quiescent Current
- ESD Protected: Above 7 kV HBM, 2 kV CDM
- GPIO / CMOS−Compatible Enable Circuitry
- 4−Bump, WLCSP 0.76 mm x 0.76 mm, 0.4 mm Pitch
- These are Pb−Free Devices

Applications

- Mobile Devices and Smart Phones
- Portable Media Devices
- Tablet PCs
- Advanced Notebook, UMPC, MID
- Portable Medical Devices
- GPS and Navigation Equipment

APPLICATION DIAGRAM

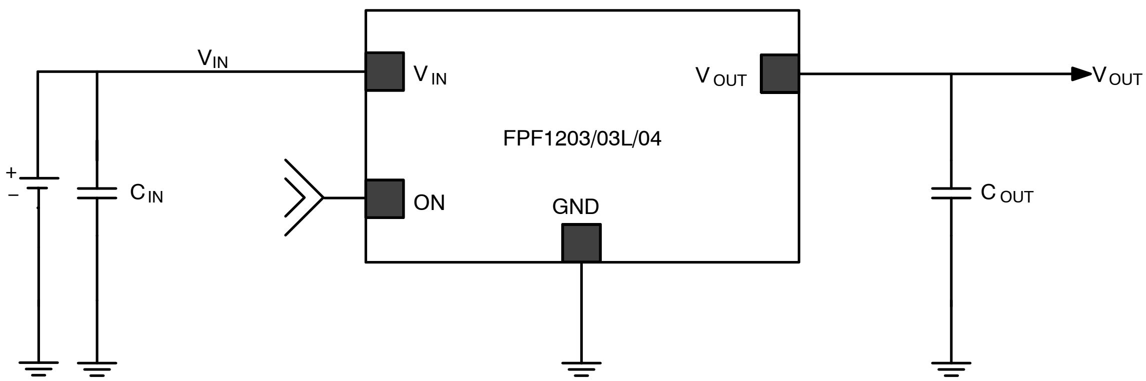


Figure 1. Typical Application

FUNCTIONAL BLOCK DIAGRAM

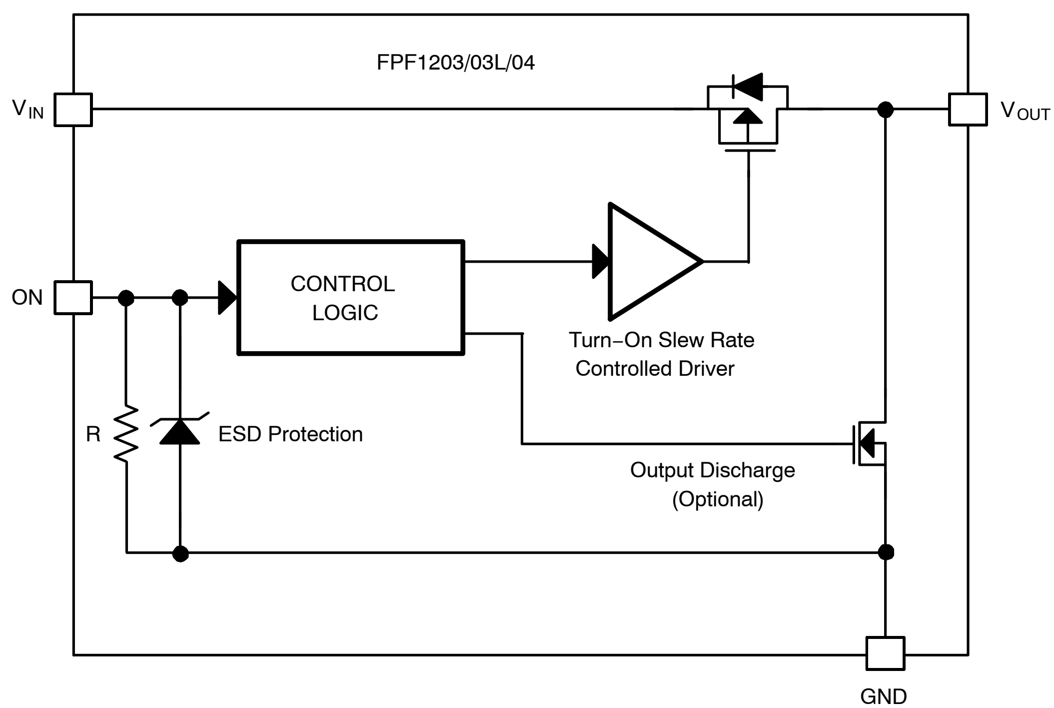


Figure 2. Functional Block Diagram (Output Discharge for FPF1204)

PIN CONFIGURATIONS

Figure 3. WLCSP Bumps Facing Down (Top View)

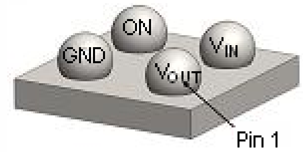


Figure 4. WLCSP Bumps Facing Up (Bottom View)

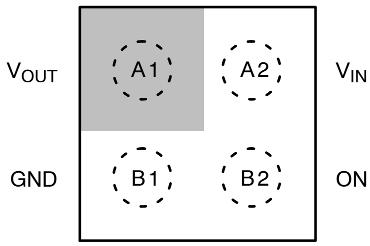


Figure 5. Pin Assignments (Top View)

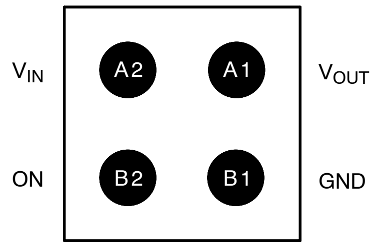


Figure 6. Pin Assignments (Bottom View)

PIN DEFINITONS

Pin No.	Name	Description
A1	V_{OUT}	Switch output
A2	V_{IN}	Supply input: input to the power switch
B1	GND	Ground
B2	ON	ON/OFF Control, active HIGH; FPF1203/04
B2	ON	ON/OFF Control, active LOW; FPF1203L

ABSOLUTE MAXIMUM RATINGS

Symbol	Parameter		Min	Max	Unit
V_{IN}	V_{IN}, V_{OUT}, V_{ON} to GND		−0.3	6.0	V
I_{SW}	Maximum Continuous Switch Current at Ambient Operating Temperature		–	2.2	A
P_D	Power Dissipation at T_A = 25°C		–	1.0	W
T_{STG}	Storage Temperature Range		−65	+150	°C
Θ_{JA}	Thermal Resistance, Junction−to−Ambient	1S2P with One Thermal Via (Note 1)	–	110	°C/W
		1S2P without Thermal Via (Note 2)	–	95	
ESD	Electrostatic Discharge Capability (Note 1, 2)	Human Body Model, JESD22−A114	7	–	kV
		Charged Device Model, JESD22−C101	2	–	

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. Measured using 2S2P JEDEC std. PCB.
2. Measured using 2S2P JEDEC PCB COLD PLATE Method.

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter	Min	Max	Unit
V_{IN}	Input Voltage	1.2	5.5	V
T_A	Ambient Operating Temperature	−40	+85	°C

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

ELECTRICAL CHARACTERISTICS (Unless otherwise noted, V_{IN} = 1.2 V to 5.5 V and T_A = −40 to +85°C. Typical values are at V_{IN} = 3.3 V and T_A = 25°C.)

Symbol	Parameter		Condition	Min	Typ	Max	Unit
BASIC OPERATION							
V_{IN}	Supply Voltage			1.2	–	5.5	V
$I_{Q(OFF)}$	Off Supply Current	FPF1203/04	V_{ON} = GND, V_{OUT} = Open, V_{IN} = 5.5 V	–	0.1	1.0	µA
		FPF1203L	V_{ON} = $V_{IN,}$ V_{OUT} = Open, V_{IN} = 5.5 V	–	1.0	2.0	
I_{SD}	Shutdown Current	FPF1203/04	V_{ON} = GND, V_{OUT} = GND	–	0.1	1.0	µA
		FPF1203L	V_{ON} = V_{IN}, V_{OUT} = GND	–	1.2	3.0	
I_Q	Quiescent Current	FPF1203/04	I_{OUT} = 0 mA, V_{ON} = V_{IN}, = 5.5 V	–	0.1	1.5	µA
		FPF1203L	I_{OUT} = 0 mA, V_{ON} = GND, $V_{IN,}$ = 5.5 V				
R_{ON}	On Resistance		V_{IN} = 5.5 V, I_{OUT} = 200 mA, T_A = 25°C	–	45	55 (Note 3)	mΩ
			V_{IN} = 3.3 V, I_{OUT} = 200 mA, T_A = 25°C	–	55	65 (Note 3)	
			V_{IN} = 1.8 V, I_{OUT} = 200 mA, T_A = 25°C	–	90	100 (Note 3)	
			V_{IN} = 1.2 V, I_{OUT} = 200 mA, T_A = 25°C	–	185	220 (Note 3)	
			V_{IN} = 1.8 V, I_{OUT} = 200 mA, T_A = 85°C (Note 3)	–	–	105	
R_{PD}	Output Discharge $R_{PULL\ DOWN}$		V_{IN} = 3.3 V, V_{ON} = OFF, I_{FORCE} = 20 mA, T_A = 25°C, FPF1204	–	65	75	Ω
V_{IH}	On Input Logic HIGH Voltage		V_{IN} = 1.2 V to 5.5 V	1.15	–	–	V
V_{IL}	On Input Logic LOW Voltage		V_{IN} = 1.2 V to 5.5 V	–	–	0.65	V
R_{ON_PD}	Pull−Down Resistance at ON Pin		V_{IN} = 1.2 V to 5.5 V	–	8.3	–	MΩ
I_{ON}	On Input Leakage		V_{ON} = V_{IN} or GND	–	–	1	µA
DYNAMIC CHARACTERISTICS							
t_{DON}	Turn−On Delay (Note 4)		V_{IN} = 3.3 V, R_L = 10 Ω, C_L = 0.1 µF, T_A = 25°C, FPF1204	–	70	–	µs
t_R	V_{OUT} Rise Time (Note 4)			–	100	–	
t_{ON}	Turn−On Time (Note 6)			–	170	–	
t_{DOFF}	Turn−Off Delay (Note 4, 5)		V_{IN} = 3.3 V, R_L = 10 Ω, C_L = 0.1 µF, T_A = 25°C, FPF1203L	–	0.5	–	µs
t_F	V_{OUT} Fall Time (Note 4, 5)			–	2.0	–	
t_{OFF}	Turn−Off Time (Note 5, 7)			–	2.5	–	
t_{DOFF}	Turn−Off Delay (Note 4, 5)		V_{IN} = 3.3 V, R_L = 500 Ω, C_L = 0.1 µF, T_A = 25°C, FPF1203L	–	6	–	µs
t_F	V_{OUT} Fall Time (Note 4, 5)			–	115	–	
t_{OFF}	Turn−Off Time (Note 5, 7)			–	121	–	
t_{DOFF}	Turn−Off Delay (Note 4, 5)		V_{IN} = 3.3 V, R_L = 10 Ω, C_L = 0.1 µF, T_A = 25°C, FPF1203	–	4.0	–	µs
t_F	V_{OUT} Fall Time (Note 4, 5)			–	2.9	–	
t_{OFF}	Turn−Off Time (Note 5, 7)			–	7.3	–	

ELECTRICAL CHARACTERISTICS (Unless otherwise noted, V_{IN} = 1.2 V to 5.5 V and T_A = −40 to +85°C. Typical values are at V_{IN} = 3.3 V and T_A = 25°C.) (continued)

Symbol	Parameter	Condition	Min	Typ	Max	Unit
DYNAMIC CHARACTERISTICS						
t_{DOFF}	Turn−Off Delay (Note 4, 5)	V_{IN} = 3.3 V, R_L = 500 Ω, C_L = 0.1 μF, T_A = 25°C, FPF1203	–	6	–	μs
t_F	V_{OUT} Fall Time (Note 4, 5)		–	115	–	
t_{OFF}	Turn−Off Time (Note 5, 7)		–	121	–	
t_{DOFF}	Turn−Off Delay (Note 4, 5)	V_{IN} = 3.3 V, R_L = 10 Ω, C_L = 0.1 μF, T_A = 25°C, FPF1204 (Note 5)	–	4.0	–	μs
t_F	V_{OUT} Fall Time (Note 4, 5)		–	2.5	–	
t_{OFF}	Turn−Off Time (Note 5, 7)		–	6.5	–	
t_{DOFF}	Turn−Off Delay (Note 4, 5)	V_{IN} = 3.3 V, R_L = 500 Ω, C_L = 0.1 μF, T_A = 25°C, FPF1204 (Note 5)	–	6	–	μs
t_F	V_{OUT} Fall Time (Note 4, 5)		–	11	–	
t_{OFF}	Turn−Off Time (Note 5, 7)		–	17	–	

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.
3. This parameter is guaranteed by design and characterization; not production tested.
4. t_{DON} / t_{DOFF} / t_R / t_F are defined in Figure 23.
5. Output discharge enabled during off−state.
6. $t_{ON} = t_R + t_{DON}$
7. $t_{OFF} = t_F + t_{DOFF}$

TYPICAL PERFORMANCE CHARACTERISTICS

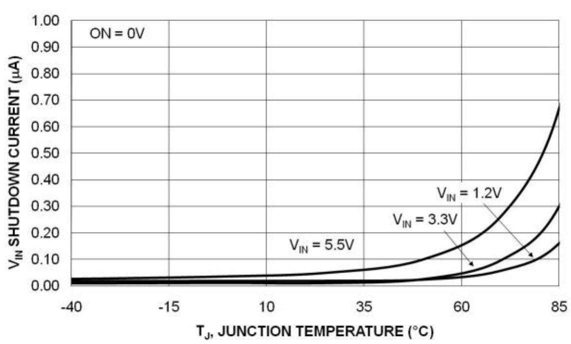


Figure 7. Shutdown Current vs. Temperature

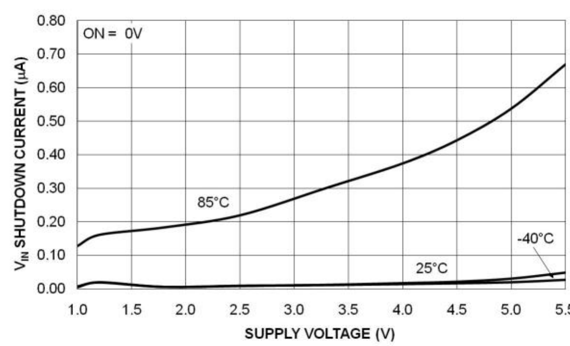


Figure 8. Shutdown Current vs. Supply Voltage

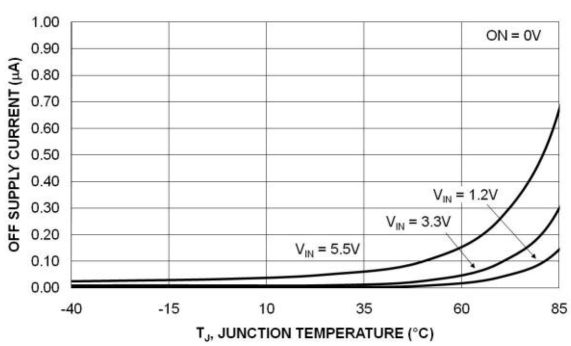


Figure 9. Off Supply Current vs. Temperature (V_{OUT} Floating)

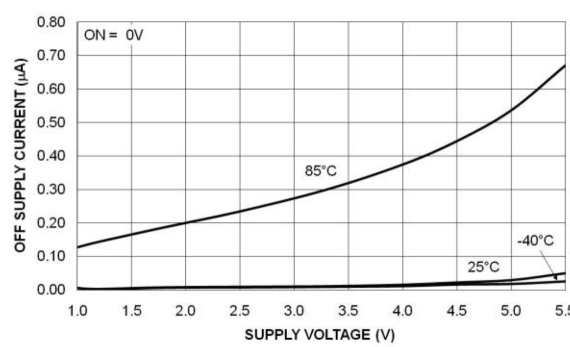


Figure 10. Off Supply Current vs. Supply Voltage (V_{OUT} Floating)

TYPICAL PERFORMANCE CHARACTERISTICS (Continued)

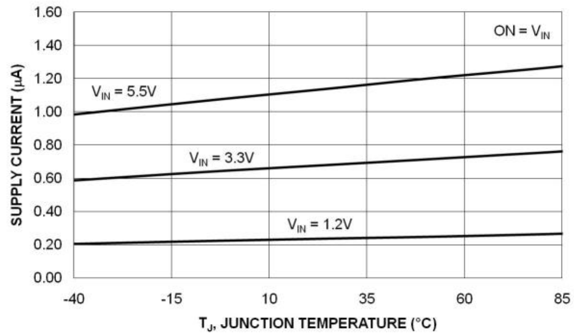


Figure 11. Quiescent Current vs. Temperature

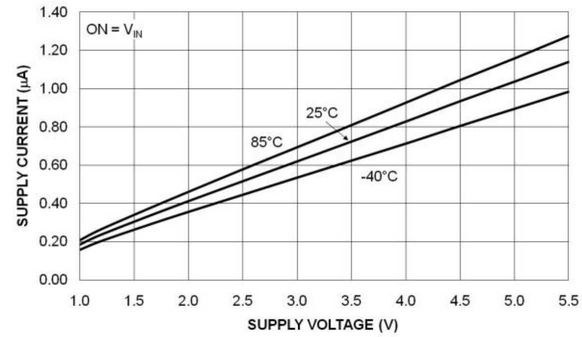


Figure 12. Quiescent Current vs. Supply Voltage

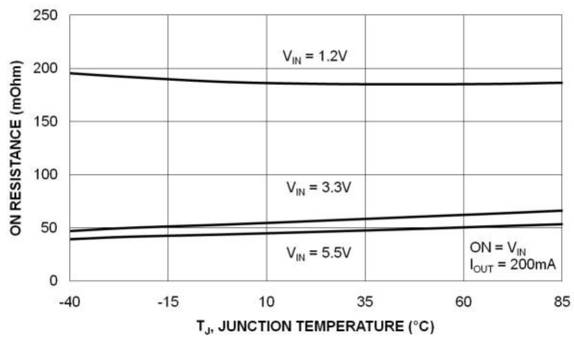


Figure 13. R_{ON} vs. Temperature

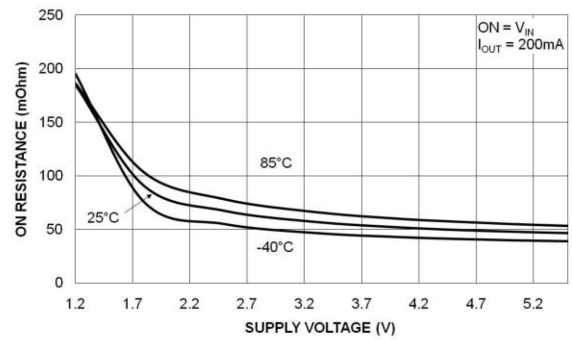


Figure 14. R_{ON} vs. Supply Voltage

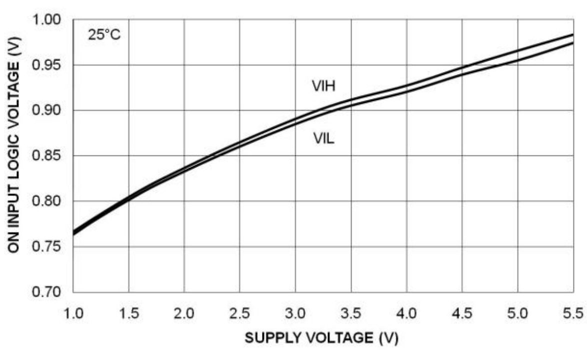


Figure 15. ON Pin Threshold vs. V_{IN}

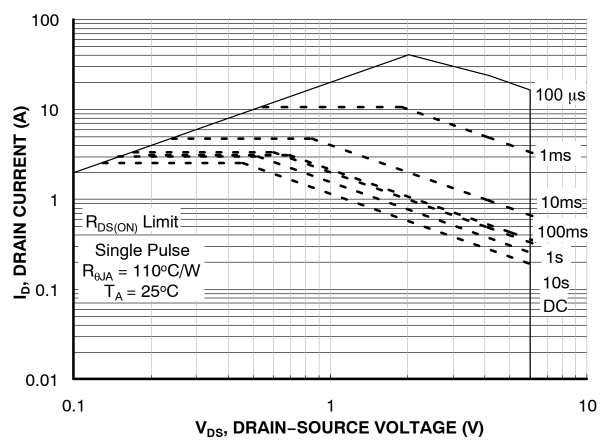


Figure 16. Drain Current vs. Drain−Source Voltage Safe Operating Area

TYPICAL PERFORMANCE CHARACTERISTICS (Continued)

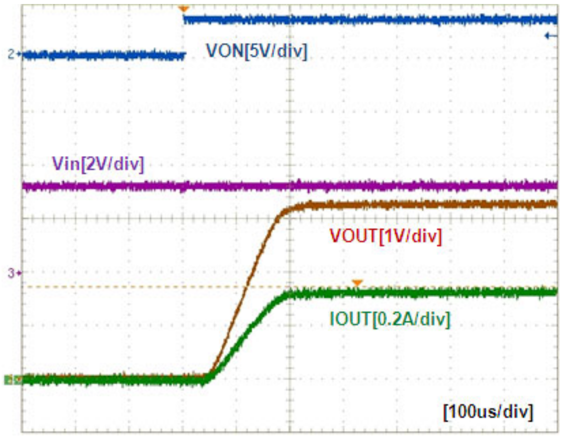


Figure 17. Turn−On Response – FPF1203 / 04 (V_{IN} = 3.3 V, C_{IN} = 1 μF, C_{OUT} = 0.1 μF, R_L = 10 Ω)

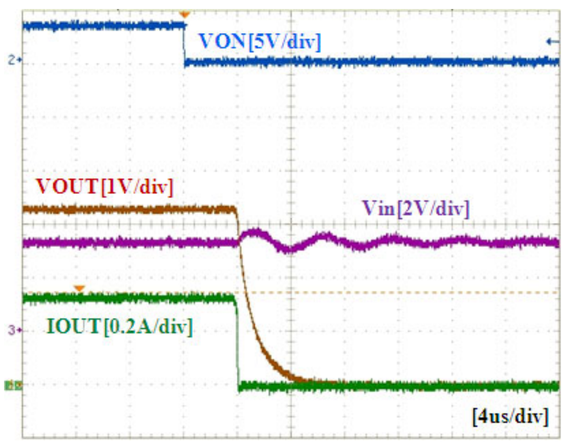


Figure 18. Turn−Off Response – FPF1203 (V_{IN} = 3.3 V, C_{IN} = 1 μF, C_{OUT} = 0.1 μF, R_L = 10 Ω)

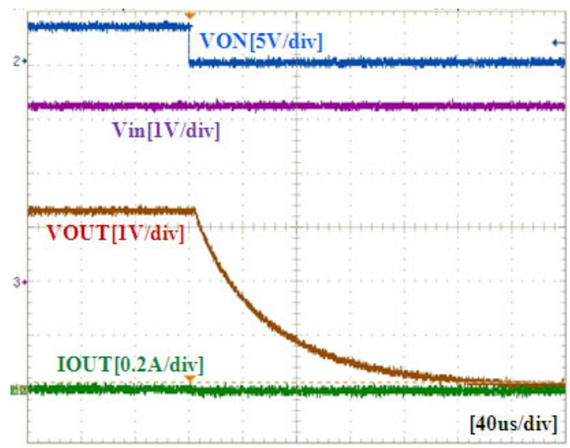


Figure 19. Turn−Off Response – FPF1203 (V_{IN} = 3.3 V, C_{IN} = 1 μF, C_{OUT} = 0.1 μF, R_L = 500 Ω)

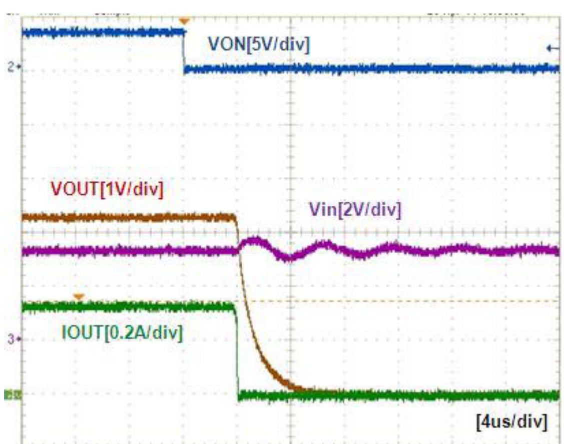


Figure 20. Turn−Off Response (V_{IN} = 3.3 V, C_{IN} = 1 μF, C_{OUT} = 0.1 μF, R_L = 10 Ω, FPF1204)

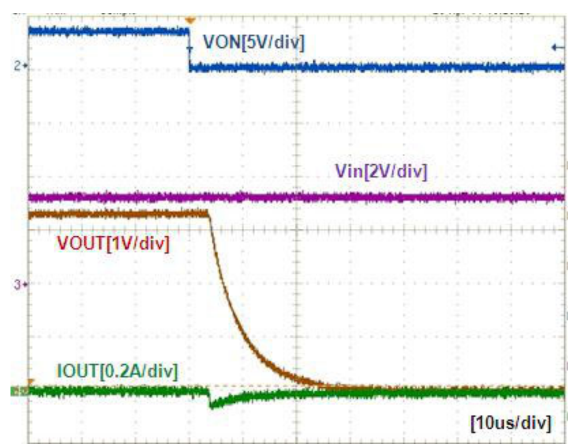


Figure 21. Turn−Off Response (V_{IN} = 3.3 V, C_{IN} = 1 μF, C_{OUT} = 0.1 μF, R_L = 500 Ω, FPF1204)

OPERATION AND APPLICATION DESCRIPTION

The FPF1203 / 03L / 04 are low−R_{ON} P−channel load switches with controlled turn−on. The core of each device is a 55 mΩ P−channel MOSFET and controller capable of functioning over a wide input operating range of 1.2 to 5.5 V.

The FPF1204 contain a 65 Ω on−chip load resistor for quick output discharge when the switch is turned off.

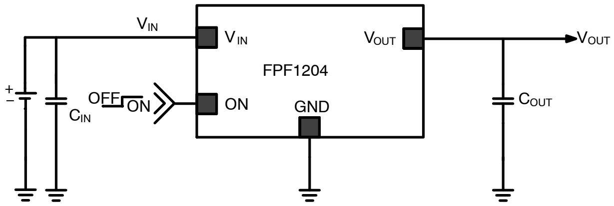


Figure 22. Typical Application

Input Capacitor

To limit the voltage drop on the input supply caused by transient inrush current when the switch turns on into a discharged load capacitor or short−circuit, a capacitor must be placed between the V_{IN} and GND pins. A 1 μF ceramic capacitor, C_{IN}, placed close to the pins is usually sufficient. Higher−value C_{IN} can be used to reduce the voltage drop in higher−current applications.

Output Capacitor

A 0.1 μF capacitor, C_{OUT}, should be placed between the V_{OUT} and GND pins. This capacitor prevents parasitic board inductance from forcing V_{OUT} below GND when the switch is on. C_{IN} greater than C_{OUT} is highly recommended. C_{OUT} greater than C_{IN} can cause V_{OUT} to exceed V_{IN} when the system supply is removed. This could result in current flow through the body diode from V_{OUT} to V_{IN}.

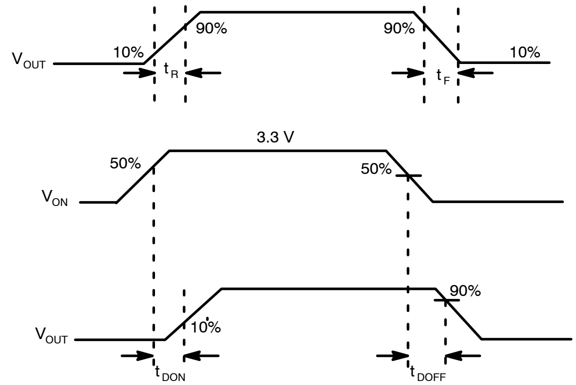


Figure 23. Timing Diagram for FPF1203/4

Board Layout

For best performance, traces should be as short as possible. To be most effective, input and output capacitors should be placed close to the device to minimize the effect of parasitic trace inductance on normal and short−circuit operation. Using wide traces or large copper planes for all pins (VIN, VOUT, ON, and GND) minimizes the parasitic electrical effects and the case−ambient thermal impedance. However, the VOUT pin should not connect directly to the battery source due to the discharge mechanism of the load switch.

ORDERING INFORMATION

Part Number	Top Mark	Switch (Typical) at $3.3V_{IN}$	Output Discharge	ON Pin Activity	t_R	Package	Shipping†
FPF1203UCX	QL	55 mΩ	NA	Active HIGH	100 μs	4−Bump, Wafer−Level Chip−Scale Package (WLCSP), 0.76 mm x 0.76 mm, 0.4 mm Pitch	3000 / Tape & Reel
FPF1203LUCX	QP	55 mΩ	NA	Active LOW	100 μs		3000 / Tape & Reel
FPF1204UCX	QM	55 mΩ	65 Ω	Active HIGH	100 μs		3000 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

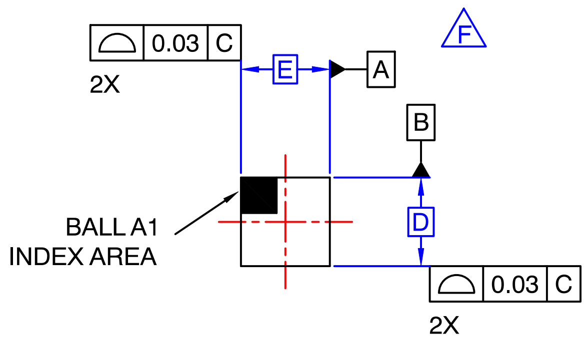
The table below pertains to the Packaging information on the following page.

PRODUCT DIMENSIONS

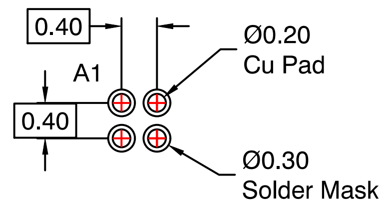
D	E	X	Y
760 μm ±30 μm	760 μm ±30 μm	0.180 mm ±0.018 μm	0.180 mm ±0.018 μm

WLCSP4 0.76x0.76x0.586
CASE 567SS
ISSUE O

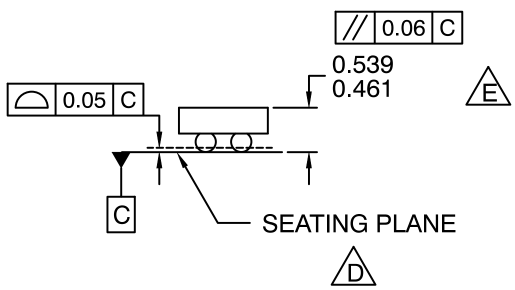
DATE 30 NOV 2016

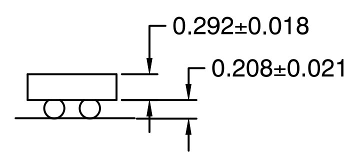


TOP VIEW

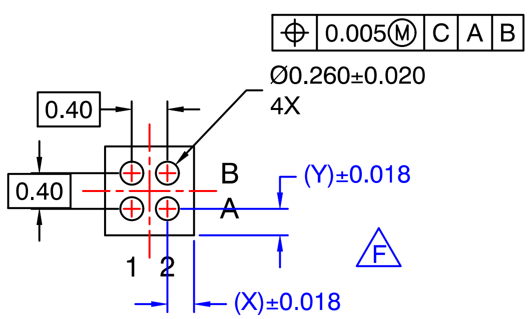


RECOMMENDED LAND PATTERN
(NSMD PAD TYPE)





SIDE VIEWS



BOTTOM VIEW

NOTES:

A. NO JEDEC REGISTRATION APPLIES.

B. DIMENSIONS ARE IN MILLIMETERS.

C. DIMENSIONS AND TOLERANCE PER ASME Y14.5M, 1994.

D. DATUM C IS DEFINED BY THE SPHERICAL CROWNS OF THE BALLS.

E. PACKAGE NOMINAL HEIGHT IS 500 MICRONS ±39 MICRONS (461–539 MICRONS).

F. FOR DIMENSIONS D, E, X, AND Y SEE PRODUCT DATASHEET.

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DESCRIPTION:	**WLCSP4 0.76x0.76x0.586**	**PAGE 1 OF 1**

PUBLICATION ORDERING INFORMATION

LITERATURE FULFILLMENT:
Email Requests to: orderlit@onsemi.com

onsemi Website: www.onsemi.com

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Phone: 011 421 33 790 2910

Europe, Middle East and Africa Technical Support:
Phone: 00421 33 790 2910
For additional information, please contact your local Sales Representative

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